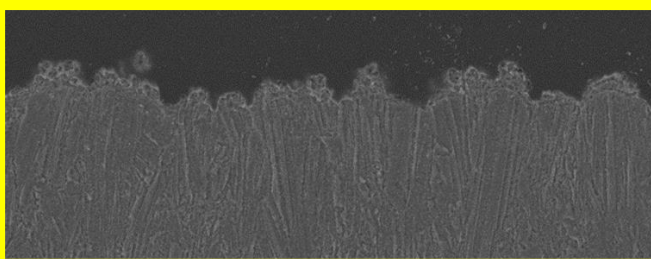


35µm untreated-side Foil SEM × 1500



35µm treated-side Foil SEM × 1500



35µm Foil Cross Section SEM × 1500

## Composition :

Resist side

– Cross Section :



Laminate Side(Bonding side )

– Resist/ Bonding Side Color : Pink/ Pink

## Application:

- HSD (High speed digital)
- Outer layer of Server/Switch/Storage
- Material: Typical substrates include polyimide and bismaleimide triazine (BT) epoxy blends, cyanate esters, polyimide and thermoplastics.

## Feature:

Technical Characteristics :

- HG310 foil with very low profile to have excellent signal integrity(SI) performance compared and etch ability to regular ED foils.
- low profile of HG310 makes it an excellent material to apply to high speed transmission board.
- With excellent anti-oxidation & shelf life.

Type	HG310		Thickness	Physical Properties							Roughness JIS94 (µm)	
				Area Wt.	Tensile(kg/mm <sup>2</sup> )		Elongation(%)		Peel Strength FR4*1			
					(oz)	(µm)	(µm)	(g/m <sup>2</sup> )	RT	180°C	RT	180°C
HG310 (Pink Color)	Toz	12µ	12±2.0	107±3	≥33	≥17	≥3	≥3	≥5.0	≥0.89	≤0.40	≤4.5
	Joz	15µ	15±2.0	125±5	≥33	≥17	≥5	≥3	≥5.5	≥0.98	≤0.40	≤5.5
	Hoz	18µ	18±2.0	153±5	≥33	≥17	≥5	≥3	≥6.5	≥1.16	≤0.40	≤6.0
	1oz	35µ	35±3.5	285±8	≥30	≥17	≥10	≥5	≥8.5	≥1.52	≤0.40	≤8.0

※ FR4 \*1 : Tg ≒ 140°C ※ This is representative data, not guarantee.